

A high-NIR sensitivity SOI-gate lock-in pixel with improved modulation contrast

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Outline

- Background
 - Overview
 - Issues with previous Pixel
- Proposed Pixel Structure
- Simulation Results
 - Potential distribution
 - Parasitic light sensitivity (PLS) and modulation contrast (M.C.)
 - Range resolution
- Summary

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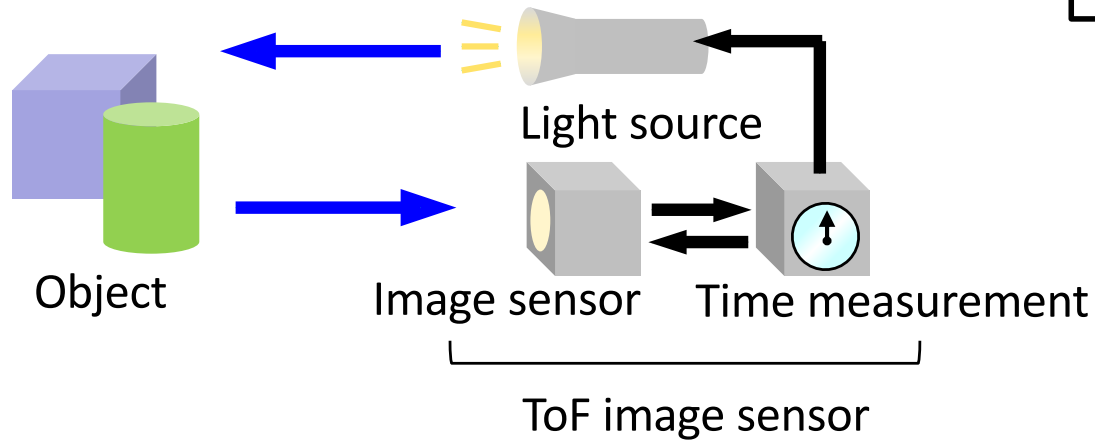
Overview

Time-of-Flight : TOF

Measure the distance to the object from T_{tof}

$$D = \frac{1}{2} c T_{tof}$$

c : velocity of light
 T_{tof} : time of flight



Advantages

- High-speed measurements
- No baseline required

Application for outdoor

- Automotive
- Drone

Outdoor long-range measurements

- Strong sunlight
⇒ Near-infrared region (NIR) light source
- Long-range measurement
⇒ High sensitivity

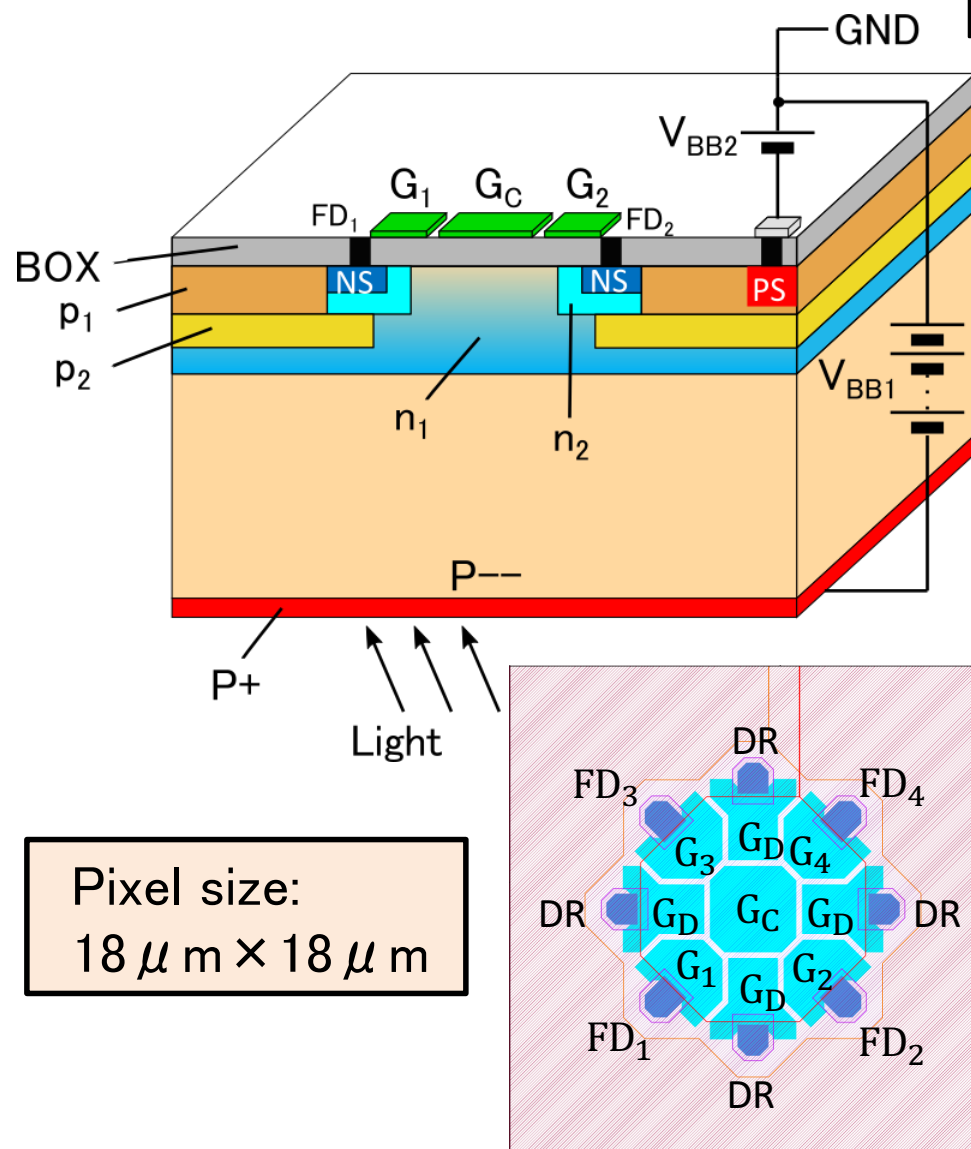


High NIR sensitivity
sensors are required

The SOI-based lock-in pixel:
Ideal QE@940nm : 96%

The SOI-based lock-in pixel[1]

[1]. S. Lee, K. Yasutomi, et al. Sensors, 20(1).



Pixel size:
 $18 \mu\text{m} \times 18 \mu\text{m}$

Features:

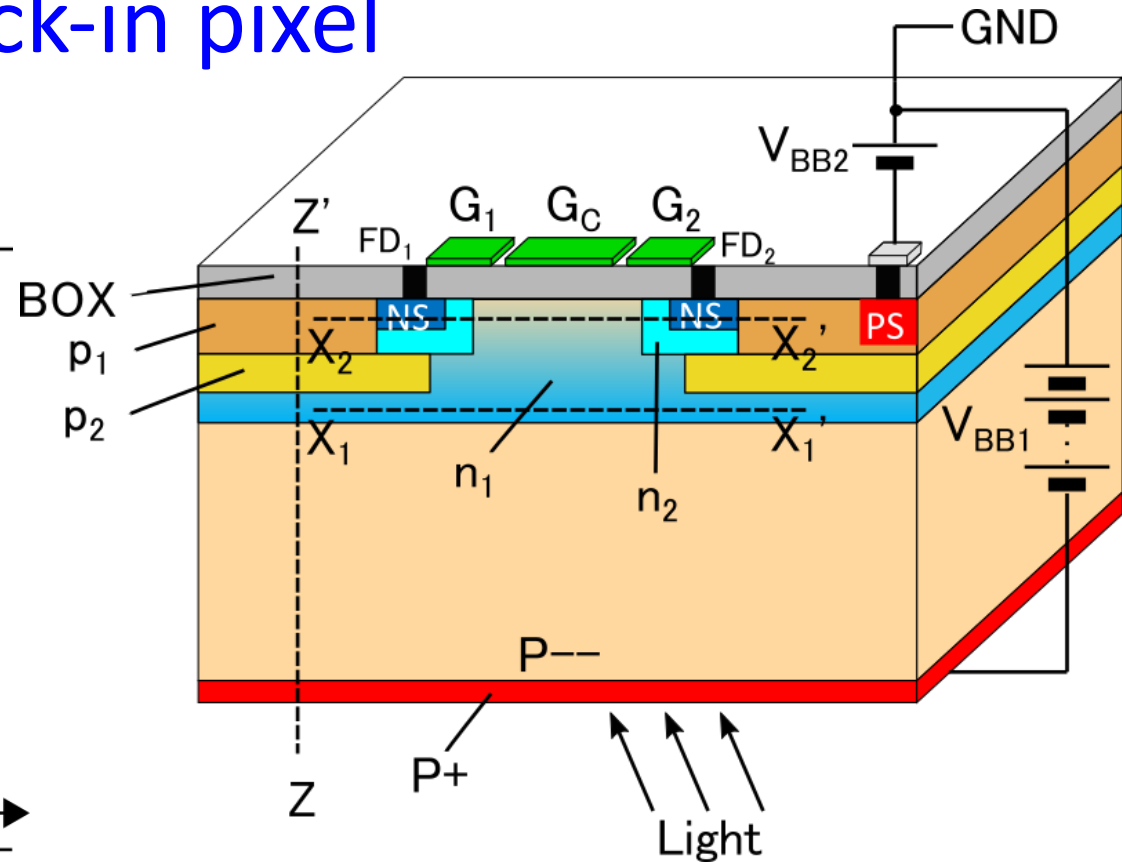
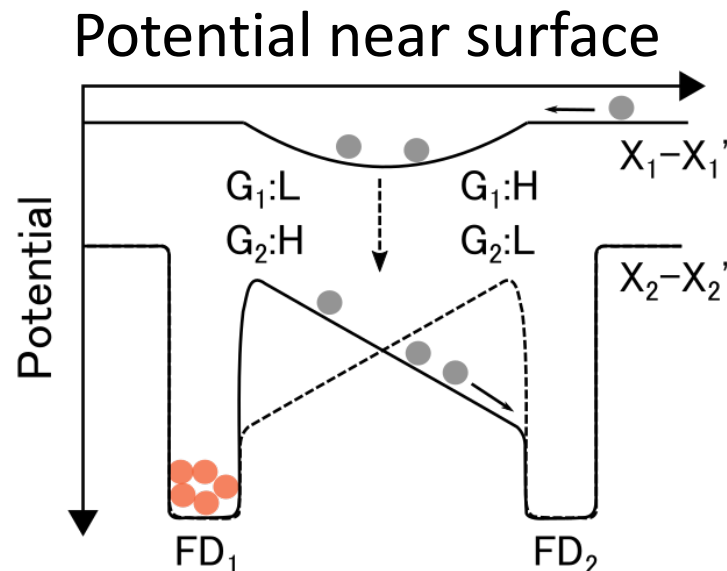
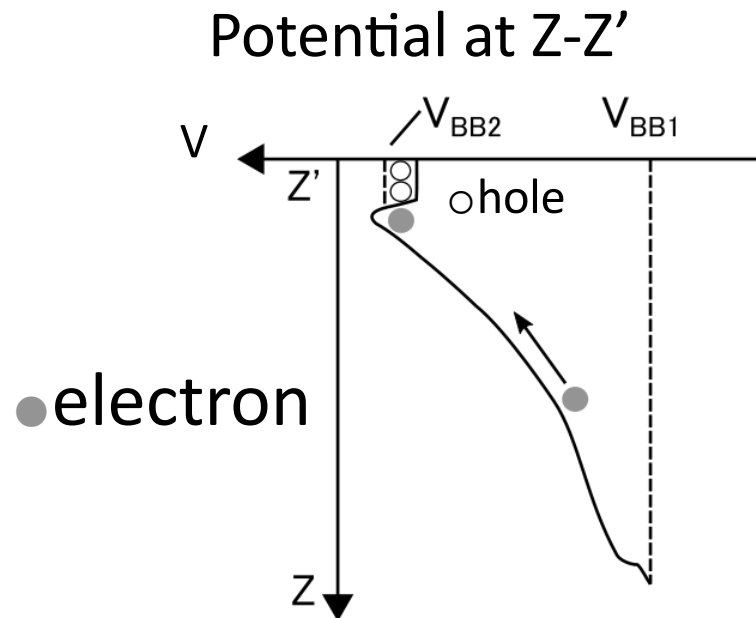
Substrate

- Thick substrates ($=150\mu\text{m}$) fully depleted by applying a high reverse bias voltage ($>100\text{V}$)
 - High fill factor due to back-side illumination
- ⇒ High QE@940nm

SOI layer

- SOI-gate
- ⇒ High-speed charge modulation
- Multi-tap structure
- ⇒ Long-range measurement and high range resolution

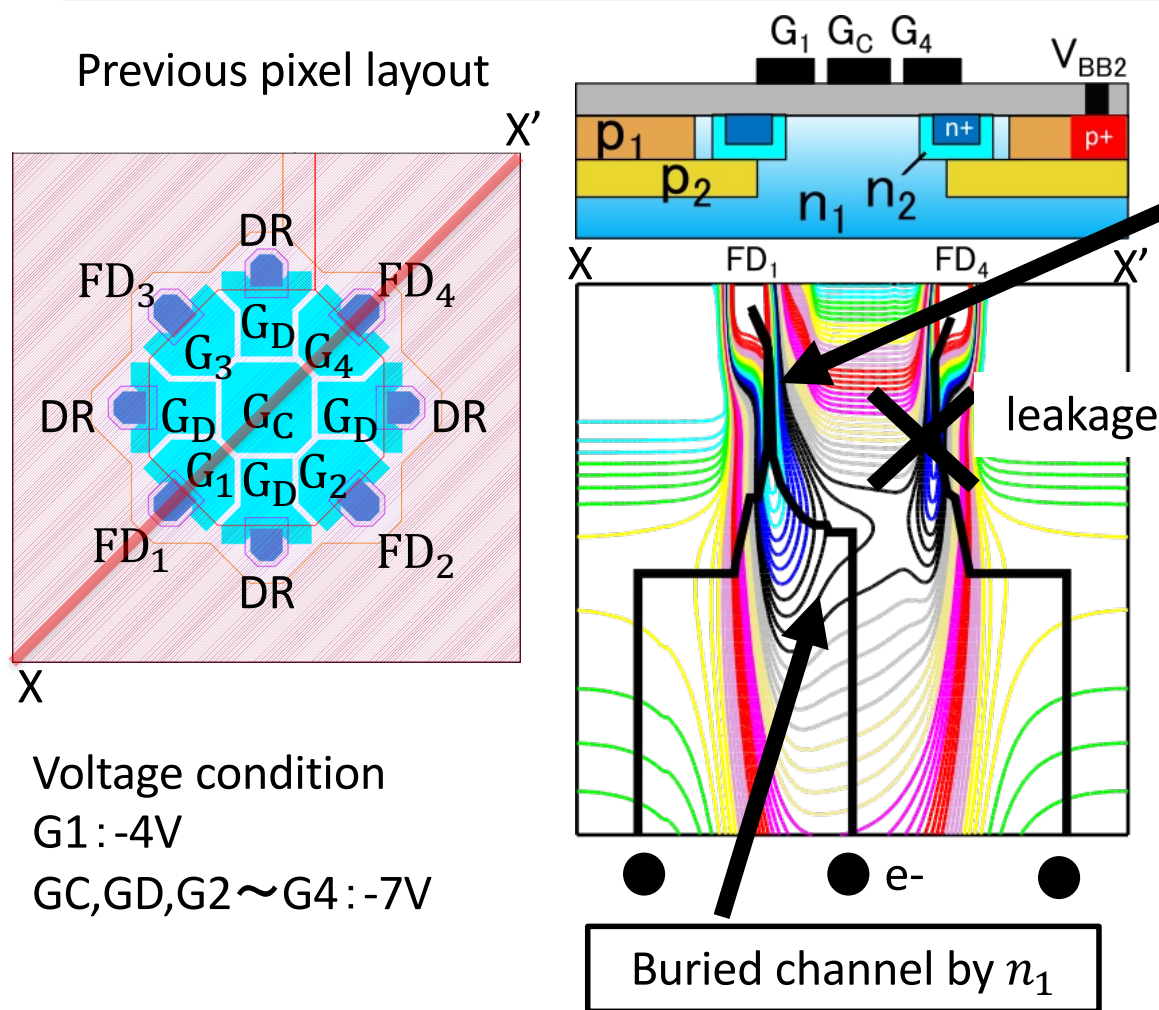
The SOI-based lock-in pixel



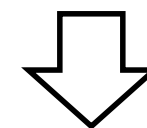
n_1 : form buried channel
 prevent a punch-through current
 n_2 : assist in charge transfer
 p_1 : fixed surface potential
 hole accumulation
 p_2 : reduce the parasitic sensitivity

The issue with previous Pixel

Issue : High parasitic light sensitivity (PLS >10%)



High n_2 concentration is required to connect buried channel and FD



The connection still exists when the modulation gate is off.
⇒ High PLS
⇒ Degradation of range resolution and internal QE

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Proposed Pixel Structure

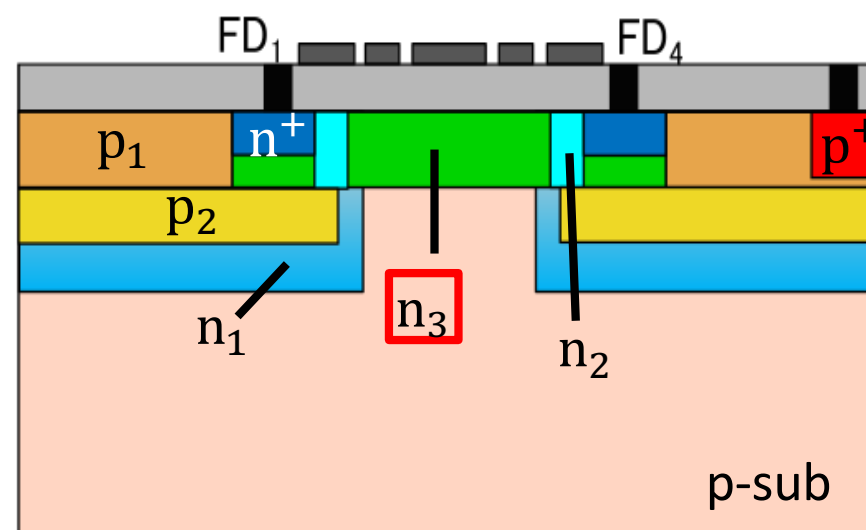
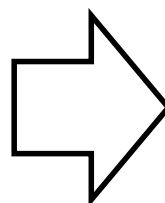
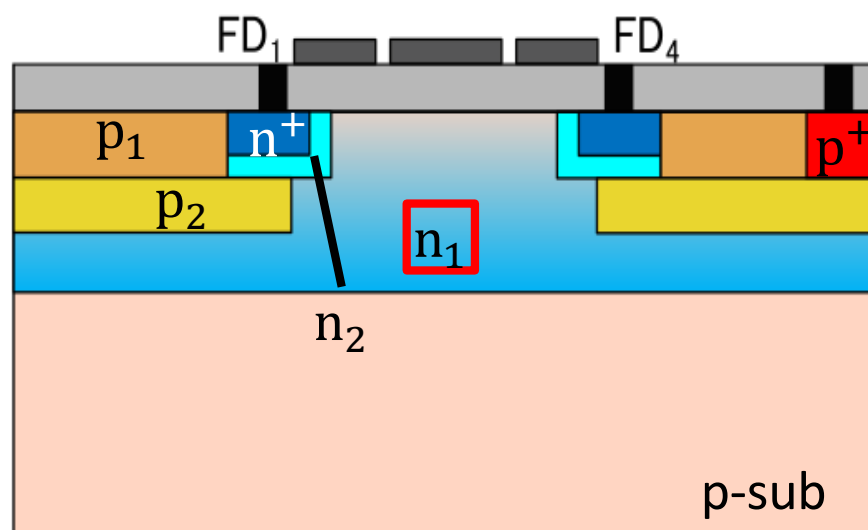
Improvement points:

- ① The shallow channel ($n_1 \Rightarrow n_3$) \Rightarrow improvement of potential controllability
- ② The additional gates \Rightarrow Enhance the lateral electric field

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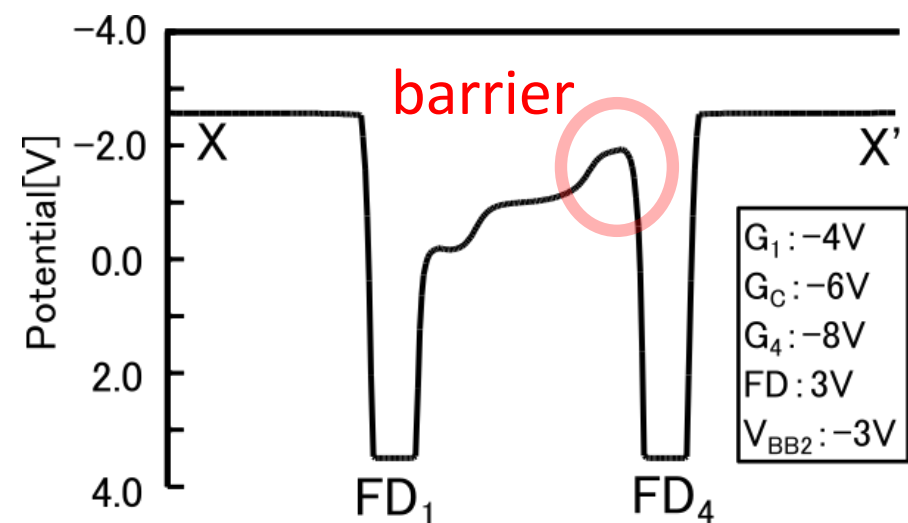
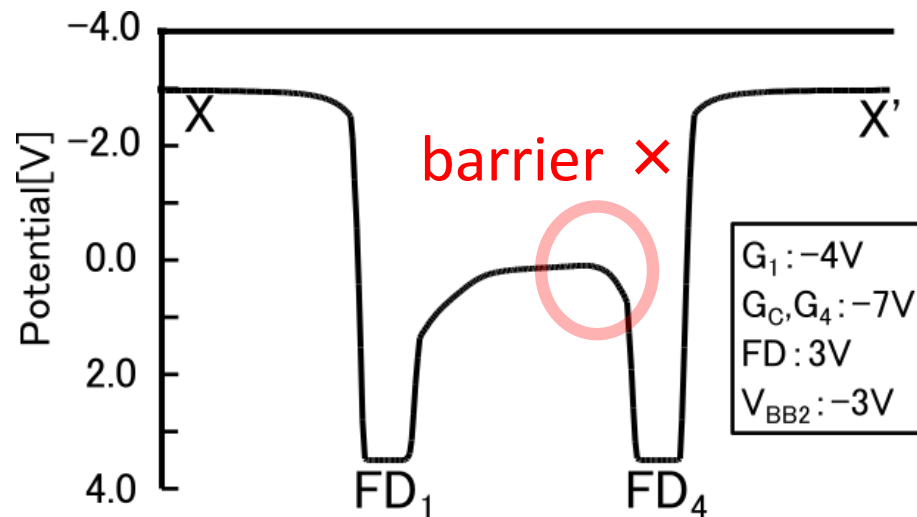
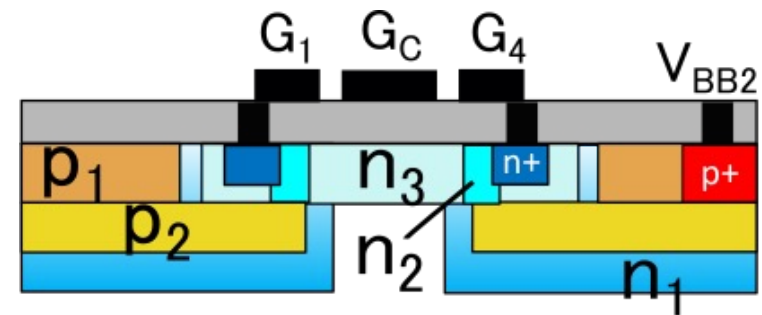
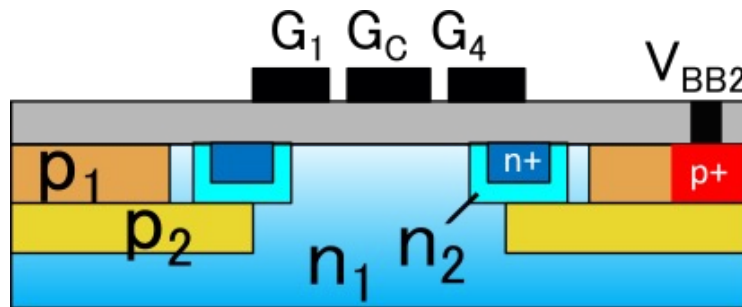
- Deeply buried channel by n_1
- Insufficient potential barrier by p_2 due to high n_2 concentration

- Shallower buried channel by n_3
- Reduction of n_2 concentration (1/3 of previous structure)
 \Rightarrow Form sufficient barrier to prevent PLS

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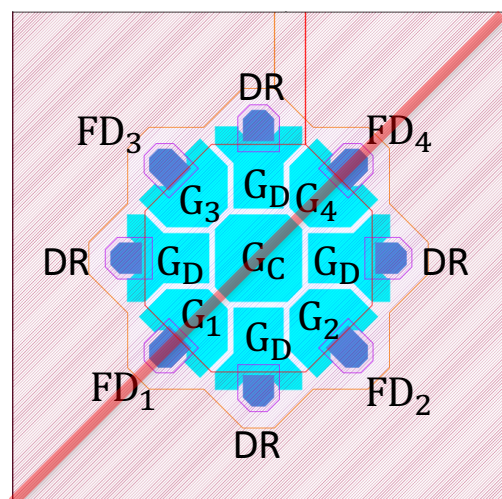


Proposed Pixel Structure

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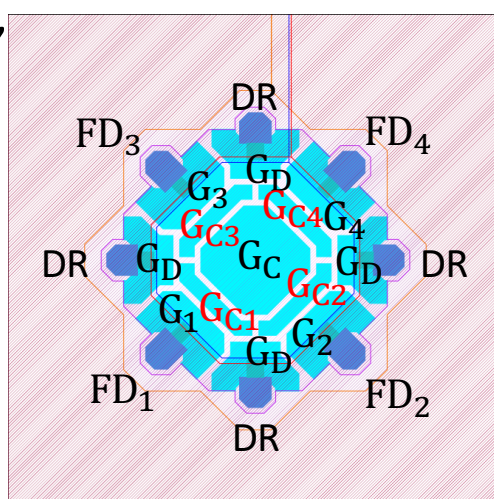
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previous pixel

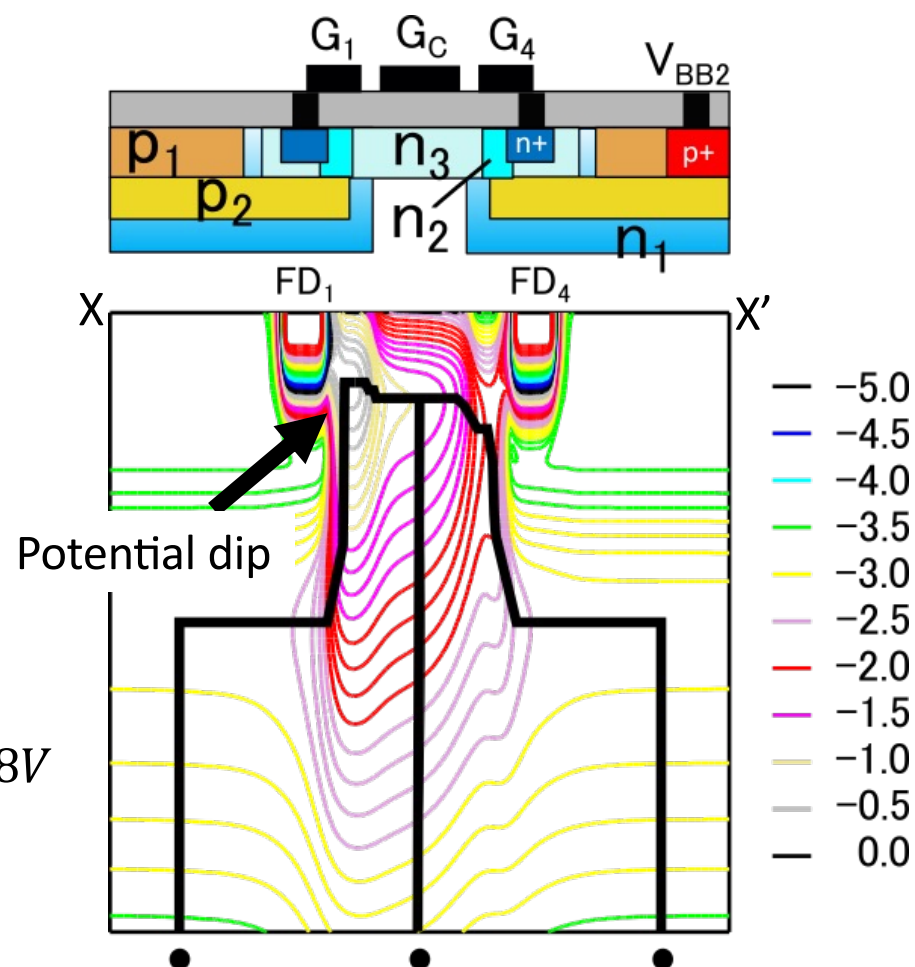


$$\begin{aligned}
 G_1 &= -4V \\
 G_C &= -6V \\
 G_2 \sim G_4, DR &= -8V \\
 FD &= 3V \\
 V_{BB2} &= -3V
 \end{aligned}$$

Proposed pixel



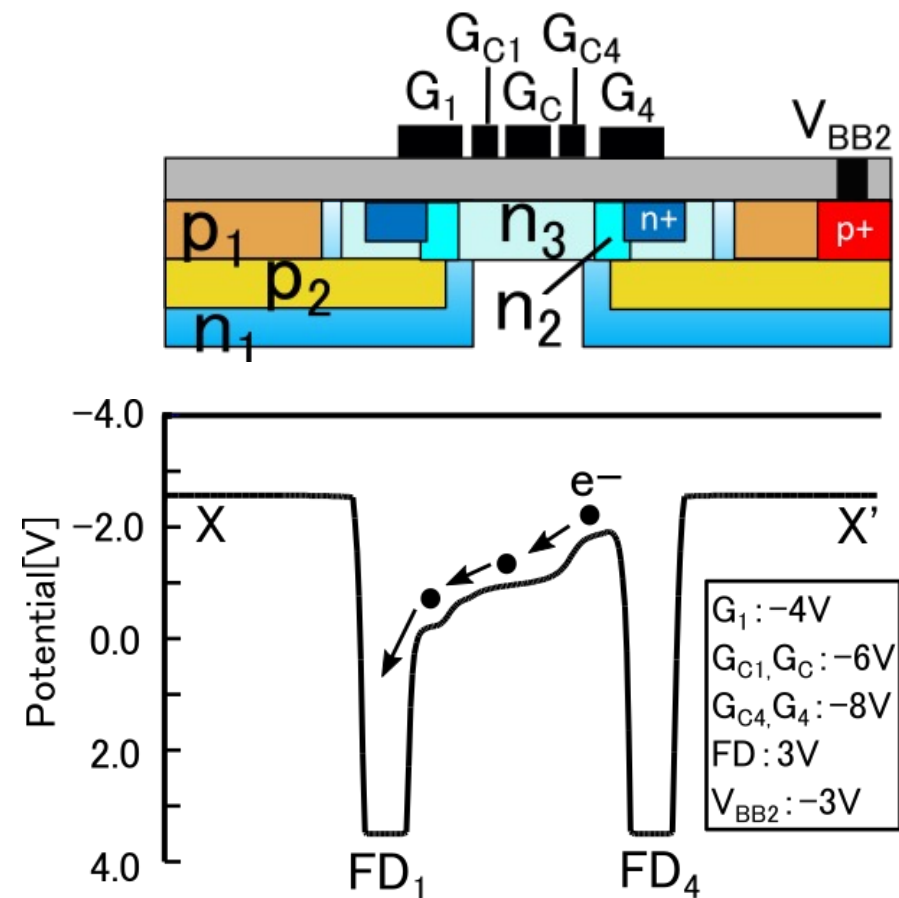
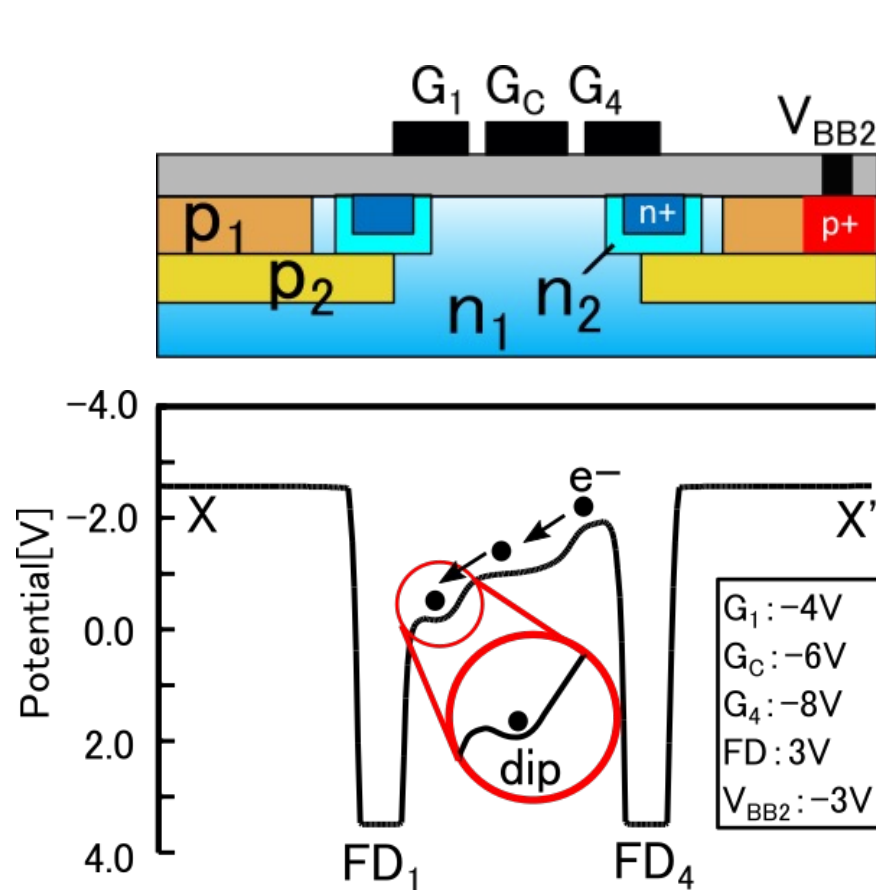
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 G_1 &= -4V \\
 G_{C1}, G_C &= -6V \\
 G_{C2} \sim G_{C4}, G_2 \sim G_4, DR &= -8V \\
 FD &= 3V \\
 V_{BB2} &= -3V
 \end{aligned}$$



Proposed Pixel Structure

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Parasitic light sensitivity (PLS) modulation contrast (MC)

✓ Simulation conditions

Light

- Light wavelength λ : **940nm**
- Light power density P_i : **271E-6[W/cm²]**
- Light pulse width: **25ns**
- A constant light with normal incidence was irradiated to the whole area of the backside.

Voltage

- Only G_1 turned on and G_2 - G_4 (GC_2 - GC_4) and GD turned off.

Previous : $G_1=-4V$, G_2 - $G_4=GC=-7V$

Proposed : $G_1=-4V$, $GC_1=GC=-6V$, GC_2 - $GC_4=G_2$ - $G_4=-8V$

✓ Definitions

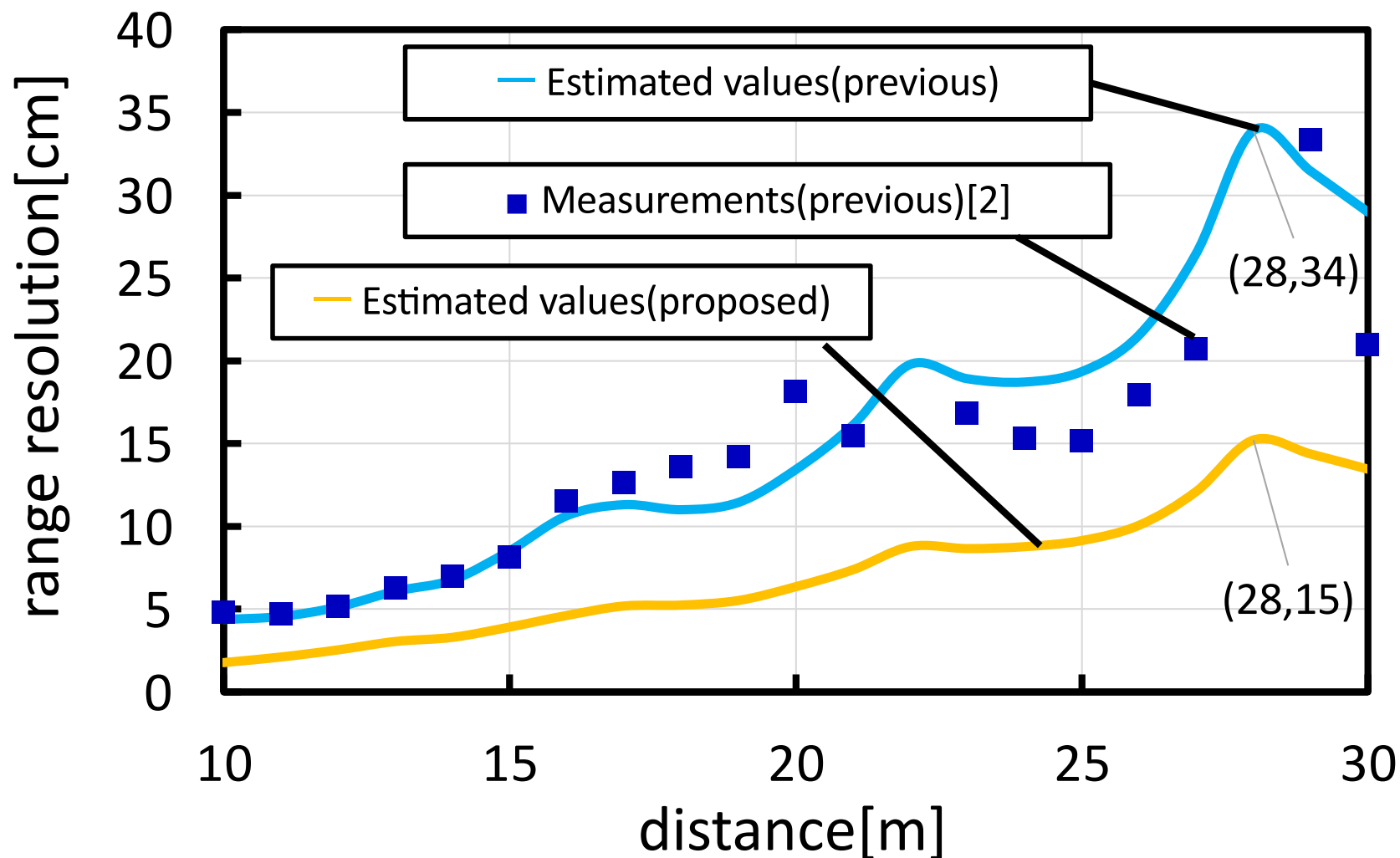
$$PLS[\%] = 100 \times \frac{I_{FD OFF}}{\sum I_{FD1} \sim I_{FD4}}$$

$$MC[\%] = 100 \times \frac{I_{FD ON}}{\sum I_{FD1} \sim I_{FD4}}$$

	Previous	Proposed
PLS[%]	13.3	0.03
MC[%]	59.7	99.9

- PLS is reduced to less than 1/400 of previous pixel ($\approx 0\%$)
- MC improves to almost 100%.

Estimated improvement of range resolution



[2]. Naoki TAKADA, Keita YASUTOMI, et al. EI2022

Summary

- We proposed a high-NIR sensitivity SOI-gate lock-in pixel with improved modulation contrast.
 - Reduction of parasitic light sensitivity (13.7% \Rightarrow 0.13%)
 - Improvements of modulation contrast (58.7% \Rightarrow 99.6%) and range resolution (28cm \Rightarrow 15cm@28m)
- Future outlook on research
 - Evaluation of prototype chip in July 2023